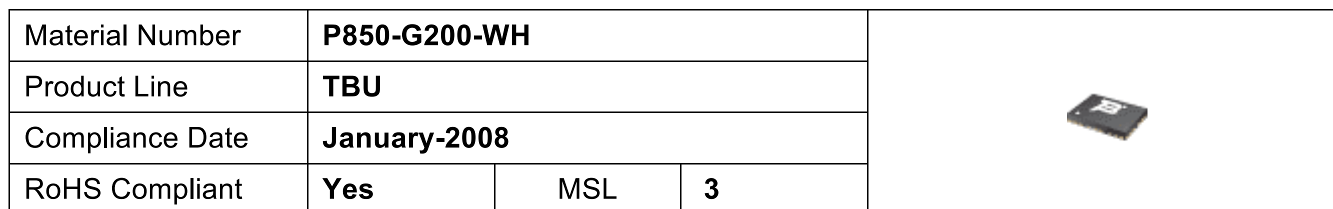
MATERIAL DECLARATION SHEET



Material Number	P850-G200-WH		
Product Line	**TBU**		
Compliance Date	**January-2008**		
RoHS Compliant	**Yes**	MSL	**3**

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Semiconductor Device	Silicon Chip	3.75	Doped silicon	7440-21-3	100	4.2	4.2
2	Lead Frame	Copper alloy with silver plating	41.48	Copper	7440-50-8	95.645	44.41	46.43
				Iron	7439-89-6	2.185	1.01	
				Tin	7440-31-5	0.034	0.02	
				Zinc	7440-66-6	0.135	0.06	
				Silver (plating)	7440-22-4	2.0	0.93	
3	Bond wire	Gold wire	0.43	Gold	7440-57-5	100	0.48	0.48
4	Die Attach	Adhesive	0.79	Di-ester resin	proprietary	3	0.03	0.88
				Functionalized ester	proprietary	7	0.06	
				Polymeric compound	proprietary	3	0.03	
				Silver	7440-22-4	87	0.76	
5	Mold compound (halogen-free)	Epoxy resin	40.11	Silica fused	60676-86-0	90.5	40.63	44.9
				Epoxy resin	proprietary	4.7	2.11	
				Phenolic resin	proprietary	4.7	2.11	
				Carbon black	1333-86-4	0.1	0.05	
6	Matte tin plating	matte tin	2.78	Tin	7440-31-5	100	3.11	3.11
		Total weight	**89.34**					

This Document was updated on: January 12, 2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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